

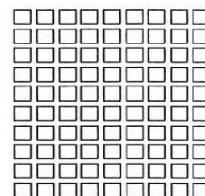
TAP2000 Mounting Procedure



Requirements for mounting the TAP2000 on a cooling plate:

- Surface roughness of cooling plate must not exceed 6.4um
- flatness of cooling plate (size of the TAP2000) 0.05mm max
- Thermal transfer compound with a heat conductivity of 2.9W/mK or better
- A suitable roller or template with max. thickness of 0.12mm

Suggested template layer:



Mounting procedure:

- Be sure that the cooling plate and resistor bottom plate are clean
- Roll on the thermal transfer compound to the bottom plate of the TAP2000
- Be careful to achieve an equal thickness of the thermal transfer compound
- The suggested quantity of the thermal compound applied to the TAP2000 when using a roller or template should be ~0.55 grams.
- Place the prepared TAP2000 onto the cooling plate.
- Move the TAP2000 a little in all directions and press down simultaneously by hand until you can move it only with higher force
- Bring the TAP2000 in position with the heatsink bore holes and bolt it with a torque of approx. 0.5Nm first, then apply 1.8Nm max as final torque to mounting screws